



Material Content Data Sheet



Sales Product Name		BSR92P H6327		Issued		24. January 2018		
MA#		MA001258310						
Package		PG-SC59-3-3		Weight*		13.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.008	0.06		572	
	noble metal	gold	7440-57-5	0.031	0.22		2218	
	inorganic material	silicon	7440-21-3	0.346	2.51	2.79	25132	27922
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		81	
	non noble metal	titanium	7440-32-6	0.006	0.04		405	
	non noble metal	chromium	7440-47-3	0.017	0.12		1216	
	non noble metal	copper	7440-50-8	5.564	40.38	40.55	403771	405473
wire	non noble metal	copper	7440-50-8	0.008	0.06	0.06	611	611
encapsulation	organic material	carbon black	1333-86-4	0.074	0.54		5351	
	plastics	epoxy resin	-	1.585	11.50		115046	
	inorganic material	silicondioxide	60676-86-0	5.714	41.47	53.51	414703	535100
leadfinish	non noble metal	tin	7440-31-5	0.258	1.87	1.87	18731	18731
plating	noble metal	silver	7440-22-4	0.168	1.22	1.22	12163	12163
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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